

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Huan-Tsung Huang	01/01/2009
Shyh-Horng Yang	12/26/2008
Yuri Masuoka	12/26/2008
Ken-Ichi Goto	12/26/2008
RECEIVING PARTY DATA	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13232154
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
Phone:	972-739-6923
Email:	linda.ingram@haynesboone.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	HAYNES AND BOONE, LLP IP Section
Address Line 1:	2323 Victory Avenue
Address Line 2:	Suite 700
Address Line 4:	Dallas, TEXAS 75219
ATTORNEY DOCKET NUMBER:	24061.1976
NAME OF SUBMITTER:	Thomas W. Kelton

OP \$40.00 13232154

Total Attachments: 6

source=1976Assignment#page1.tif

source=1976Assignment#page2.tif

source=1976Assignment#page3.tif

source=1976Assignment#page4.tif

source=1976Assignment#page5.tif

source=1976Assignment#page6.tif

ASSIGNMENT

WHEREAS, we,

- (1) Huan-Tsung Huang of 6F, #59 Chengggong 1st Street
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.
- (2) Shyh-Horng Yang of 13F-1, No. 153, Lane 89, Sec. 1, Kuangfu Road
Hsinchu, Taiwan, R.O.C.
- (3) Yuri Masuoka of 15F #126 Shengli 1st Road
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.
- (4) Ken-Ichi Goto of 89, 2-1, 9F-1, Su-Wei Road
Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

**LOCAL CHARGE AND WORK FUNCTION
ENGINEERING ON MOSFET**

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on _____ and assigned application no. _____ and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

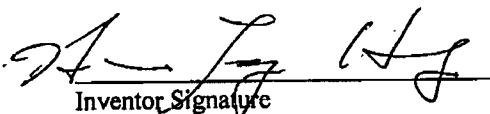
AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Huan-Tsung Huang

Residence Address: 6F, #59 Chengggong 1st Street
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: 2009.1.1


Inventor Signature

Inventor Name: Shyh-Horng Yang

Residence Address: 13F-1, No. 153, Lane 89, Sec. 1, Kuangfu Road
Hsinchu, Taiwan, R.O.C.

Dated: _____

Inventor Signature

ASSIGNMENT

WHEREAS, we,

- (1) Huan-Tsung Huang of 6F, #59 Chengggong 1st Street
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.
- (2) Shyh-Horng Yang of 13F-1, No. 153, Lane 89, Sec. 1, Kuangfu Road
Hsinchu, Taiwan, R.O.C.
- (3) Yuri Masuoka of 15F #126 Shengli 1st Road
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.
- (4) Ken-Ichi Goto of 89, 2-1, 9F-1, Su-Wei Road
Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

**LOCAL CHARGE AND WORK FUNCTION
ENGINEERING ON MOSFET**

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on and assigned application no. and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Docket No.: 2008-0517 / 24061.1146
Customer No.: 42717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Huan-Tsung Huang

Residence Address: 6F, #59 Chengggong 1st Street
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.

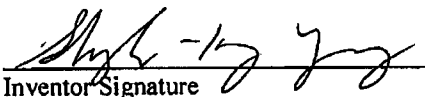
Dated: _____

Inventor Signature

Inventor Name: Shyh-Horng Yang

Residence Address: 13F-1, No. 153, Lane 89, Sec. 1, Kuangfu Road
Hsinchu, Taiwan, R.O.C.

Dated: 12/26/08



Inventor Signature

ASSIGNMENT

WHEREAS, we,

- (1) Huan-Tsung Huang of 6F, #59 Chengggong 1st Street
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.
- (2) Shyh-Horng Yang of 13F-1, No. 153, Lane 89, Sec. 1, Kuangfu Road
Hsinchu, Taiwan, R.O.C.
- (3) Yuri Masuoka of 15F #126 Shengli 1st Road
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.
- (4) Ken-Ichi Goto of 89, 2-1, 9F-1, Su-Wei Road
Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

**LOCAL CHARGE AND WORK FUNCTION
ENGINEERING ON MOSFET**

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on _____ and assigned application no. _____ and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Docket No.: 2008-0517 / 24061.1146
Customer No.: 42717

Inventor Name: Yuri Masuoka

Residence Address: 15F #126 Shengli 1st Road
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: 12/26/2008


Inventor Signature

Inventor Name: Ken-Ichi Goto

Residence Address: 89, 2-1, 9F-1, Su-Wei Road East District
Hsin-Chu, Taiwan, R.O.C.

Dated: 12/26/08


Inventor Signature
